

Technical data sheet

**PROPERTIES
THERMAL E**

The values are measured on standard Thermal E, with copper surface of 35µ, dielectric of 0.10mm, aluminium of 1.50 mm.

Produced with epoxy multifunctional and dysfunctional epoxy resin

DIELECTRIC LAYERS CHARACTERISTICS

DIELECTRIC CONSTANT 1 MHz	4.7
DISSIPATION FACTOR	0.018.
TMA-T260 Min	13
Tma-t300 Min	0
TDA – TD 5% WT loss °C	315
HPCT (2 h) + 20 sec dip.288°C	100% pass
Average Z CTE 40-200°C ppm/K	160
<i>Dielectric thickness available = 0.10mm – 0.20 mm</i>	

**COMPOSITE LAMINATE
DENOMINATION : THERMAL E**

THERMAL E is a composite laminate with copper, prepreg, epoxy or modified epoxy resin and aluminium Alloy

<i>APPLICATIONS</i>	<i>For all the applications where the thermal dissipation of the heat is needed, with or without SMD components</i>
<i>STANDARD CONSTRUCTION</i>	<i>ALUMINIUM thickness in mm : 0.8 – 1.0 – 1.5 – 2.0 – 3.0</i>
<i>INSULATING PREPREG</i>	<i>0.10 mm – 0.20 mm</i>
<i>STANDARD SIZES</i>	<i>400mm X 500mm - 460mm X 610mm</i>
<i>COPPER µ</i>	<i>18µ - 35µ - 70µ - 105µ - 140µ - 400µ</i>
<i>THERMAL E PROTECTION PURPOSES</i>	<i>Alu side protection with dry film Alu side protection with dry film and Mylar Alu and copper side protection with dry film</i>